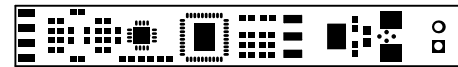
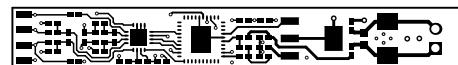


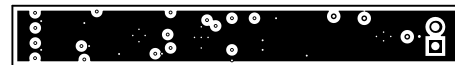
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: TIDM-01000 | | |
| PLOT NAME = Top Overlay | GENERATED : 3/4/2018 3:30:11 PM | TEXAS INSTRUMENTS | |



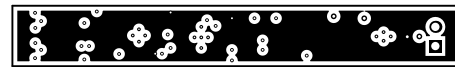
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: TIDM-01000 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 3/4/2018 3:30:14 PM | TEXAS INSTRUMENTS | |



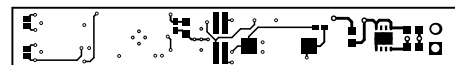
| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: TIDM-01000 | | |
| PLOT NAME = Top Layer | GENERATED : 3/4/2018 3:30:17 PM | TEXAS INSTRUMENTS | |



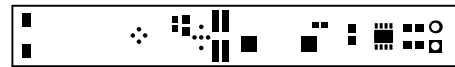
| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = GND | TID #: TIDM-01000 | | |
| PLOT NAME = GND | GENERATED : 3/4/2018 | 3:30:21 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = UCC | TID #: TIDM-01000 | | |
| PLOT NAME = UCC | GENERATED : 3/4/2018 | 3:30:25 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: TIDM-01000 | | |
| PLOT NAME = Bottom Layer | GENERATED : 3/4/2018 | 3:30:29 PM | TEXAS INSTRUMENTS |

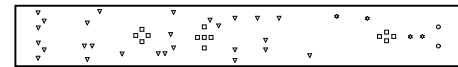


| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: TIDM-01000 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 3/4/2018 | 3:30:33 PM | TEXAS INSTRUMENTS |

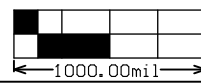
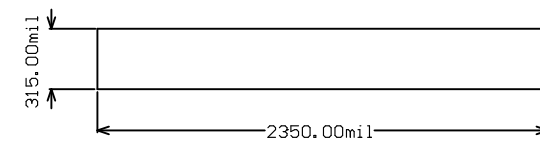


| | | | |
|----------------------------------|---------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: TIDM-01000 | | |
| PLOT NAME = Bottom Overlay | GENERATED : 3/4/2018 3:30:37 PM | TEXAS INSTRUMENTS | |

| Symbol | Quantity | Finished Hole Size | Plated | Hole Type | Drill Layer Pair | Hole Tolerance |
|--------|----------|--------------------|--------|-----------|--------------------------|----------------|
| □ | 13 | 7.87mil (0.200mm) | PTH | Round | Top Layer - Bottom Layer | |
| ▽ | 27 | 10.00mil (0.254mm) | PTH | Round | Top Layer - Bottom Layer | |
| ✱ | 4 | 15.00mil (0.381mm) | PTH | Round | Top Layer - Bottom Layer | |
| ○ | 2 | 43.31mil (1.100mm) | PTH | Round | Top Layer - Bottom Layer | |
| | 46 Total | | | | | |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: TIDM-01000 | | |
| PLOT NAME = Drill Drawing | GENERATED : 3/4/2018 | 3:30:40 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: TIDM-01000 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: TIDM-01000 | | |
| PLOT NAME = Board Dimensions | GENERATED : 3/4/2018 | 3:30:45 PM | TEXAS INSTRUMENTS |

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